

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. - 6. (Canceled)

7. (Currently Amended) A substrate processing method ~~including~~ comprising:
a first step of supplying an alkaline solution to a surface of a substrate;
a second step of supplying an acid solution to the surface of said substrate after said first step; and
a third step of supplying said alkaline solution to the surface of said substrate after said second step, wherein
~~at least either supply of said acid solution in said second step or supply~~said supplying of
said alkaline solution in said first step and said third step comprises injection of droplets formed by mixing said alkaline solution with gas, and
said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water.

8. (Original) The substrate processing method according to claim 7, wherein only supply of said alkaline solution in said first step and said third step is injection of droplets formed by mixing said alkaline solution with gas.

9. (Canceled)

10. (Currently Amended) The substrate processing method according to claim [[9]] 8, wherein
said acid solution is a mixed solution containing hydrochloric acid and hydrofluoric acid.

11. (Currently Amended) A substrate processing method ~~including~~ comprising:
a first step of supplying an alkaline solution to a surface of a substrate;

a second step of supplying an acid solution to the surface of said substrate after said first step; and

a third step of supplying said alkaline solution to the surface of said substrate after said second step, wherein

~~at least either supply of said acid solution in said second step or supply of said alkaline solution in said first step and~~ said third step comprising supplying of said alkaline solution subjected to megasonic vibrations, and

said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water.

12. (Previously Presented) The substrate processing method according to claim 11, wherein

only the supply of said alkaline solution in said first step and said third step is performed with said alkaline solution subjected to megasonic vibrations.

13. (Canceled)

14. (Currently Amended) The substrate processing method according to claim [[13]] 12, wherein

said acid solution is a mixed solution containing hydrochloric acid and hydrofluoric acid.

15. - 20. (Canceled)

21. (Previously Presented) The substrate processing method according to claim 7, said alkaline solution and said acid solution being at an ordinary temperature.

22. (Previously Presented) The substrate processing method according to claim 21, wherein

said alkaline solution has a pH value of at least 11 and less than 13.

23. (Previously Presented) The substrate processing method according to claim 11,
said alkaline solution and said acid solution being at an ordinary temperature.

24. (Previously Presented) The substrate processing method according to claim 23, wherein
said alkaline solution has a pH value of at least 11 and less than 13.

25. - 26. (Canceled)

27. (Previously Presented) The substrate processing method according to claim 7,
wherein droplets of said alkaline solution are injected from a nozzle to said surface of said substrate in said first step.

28. (Previously Presented) The substrate processing method according to claim 11, wherein droplets of said alkaline solution are injected from a nozzle to said surface of said substrate in said first step.

29. (New) A substrate processing method comprising:
a first step of supplying an alkaline solution to a surface of a substrate;
a second step of supplying an acid solution to the surface of said substrate after said first step; and
a third step of supplying said alkaline solution to the surface of said substrate after said second step, wherein
supply of said acid solution in said second step comprises injection of droplets formed by mixing said acid solution with gas, and
said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water.

30. (New) A substrate processing method comprising:
a first step of supplying an alkaline solution to a surface of a substrate;
a second step of supplying an acid solution to the surface of said substrate after said first step; and
a third step of supplying said alkaline solution to the surface of said substrate after said second step, wherein
supply of said acid solution in said second step comprises supplying of said acid solution subjected to megasonic vibrations, and
said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water.